

## Nch 200V 8.0A Power MOSFET

V <sub>DSS</sub>	200V
R <sub>DS(on)</sub> (Max.)	$770 \mathrm{m}\Omega$
I <sub>D</sub>	8.0A
$P_D$	40W

RCJ081N20

## Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

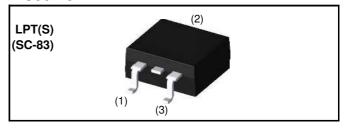
## Application

Switching Power Supply

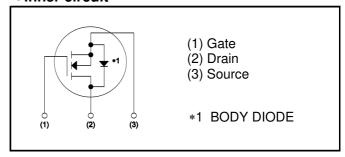
**Automotive Motor Drive** 

Automotive Solenoid Drive

#### Outline



## ●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Typo	Tape width (mm)	24
Type	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ081N20

## • Absolute maximum ratings( $T_a = 25$ °C)

	\ α /			
Paramete	Symbol	Value	Unit	
Drain - Source voltage	$V_{DSS}$	200	V	
Continuous drain current	T <sub>c</sub> = 25°C	I <sub>D</sub> *1	±8.0	Α
Continuous drain current	T <sub>c</sub> = 100°C	I <sub>D</sub> *1	±4.3	А
Pulsed drain current		I <sub>D,pulse</sub> *2	±32	А
Gate - Source voltage		$V_{GSS}$	±30	V
Avalanche energy, single pulse	9	E <sub>AS</sub> *3	5.17	mJ
Avalanche current		I <sub>AR</sub> *3	4.0	А
$T_c = 25^{\circ}C$		P <sub>D</sub>	40	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P <sub>D</sub>	1.56	W
Junction temperature		T <sub>j</sub>	150	°C
Range of storage temperature	T <sub>stg</sub>	-55 to +150	°C	

## ●Thermal resistance

Parameter	Symbol	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	$R_{thJC}$	-	-	3.125	°C/W
Thermal resistance, junction - ambient *4	$R_{thJA}$	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# •Electrical characteristics( $T_a = 25$ °C)

Parameter	Symbol Conditions		Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$ , $I_D = 1mA$	200	-	-	V
Zoro gato voltago drain current	lana	$V_{DS} = 200V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	1	-	10	^
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS} = 200V, V_{GS} = 0V$ $T_j = 125^{\circ}C$	-	1	100	μΑ
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 30V, \ V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS (th)</sub>	$V_{DS} = 10V$ , $I_D = 1mA$	3.25	-	5.25	V
		$V_{GS} = 10V, I_D = 4.0A$	-	550	770	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 4.0A$ $T_j = 125^{\circ}C$	-	1100	1540	mΩ
Forward transfer admittance	$g_{fs}$	$V_{DS} = 10V, I_{D} = 4.0A$	1.0	2.0	-	S

# ●Electrical characteristics(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
raiainetei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0V$	-	330	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	33	-	pF
Reverse transfer capacitance	$C_{rss}$	f = 1MHz	-	15	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 100V, V_{GS} = 10V$	-	13	-	
Rise time	t <sub>r</sub> *5	$I_D = 4.0A$	-	20	-	no
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L = 25\Omega$	-	18	-	ns
Fall time	t <sub>f</sub> *5	$R_G = 10\Omega$	-	8	-	

# •Gate Charge characteristics( $T_a = 25$ °C)

Doromotor	Symbol	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	$Q_g^{*5}$	$V_{DD} \simeq 100V$	-	8.5	1	
Gate - Source charge	Q <sub>gs</sub> *5	$I_{D} = 8.0A$	-	3.4	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	$V_{GS} = 10V$	-	3.4	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \approx 100V, I_D = 8.0A$	-	7.9	-	V

# ●Body diode electrical characteristics (Source-Drain)(T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
raiailletei	Syllibol	Symbol Conditions -		Тур.	Max.	Offic	
Continuous source current	l <sub>S</sub> *1	T <sub>c</sub> = 25°C	-	-	8.0	Α	
Pulsed source current	I <sub>SM</sub> *2	1 c = 23 0	-	-	32	Α	
Forward voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_S = 8.0A$	-	-	1.5	V	
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 4.0A	-	75	-	ns	
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/μs	-	210	-	nC	

<sup>\*1</sup> Limited only by maximum temperature allowed.

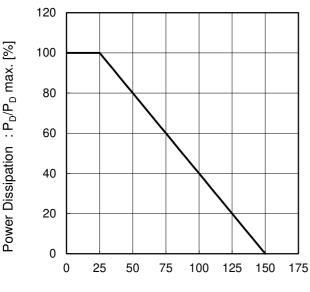
\*5 Pulsed

<sup>\*2</sup> Pw  $\leq$  10 $\mu$ s, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\simeq}$  500 $\mu$ H,  $V_{DD}$  = 50V, Rg = 25 $\Omega$ , starting  $T_j$  = 25°C

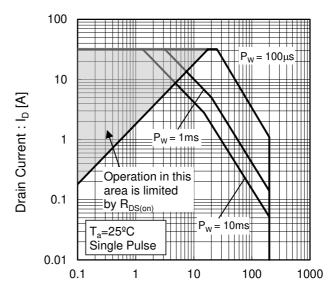
<sup>\*4</sup> Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve



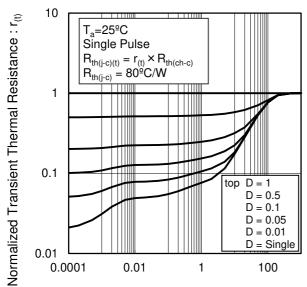
Junction Temperature : T<sub>i</sub> [°C]

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width: Pw[s]

Fig.4 Avalanche Current vs Inductive Load

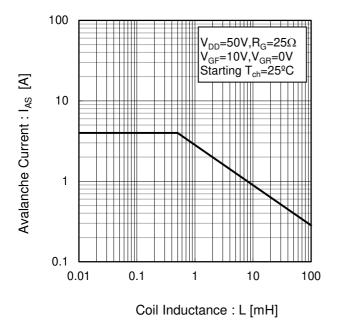
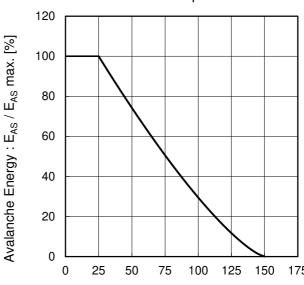
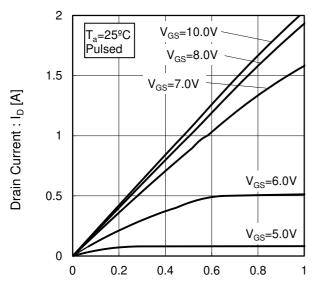


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



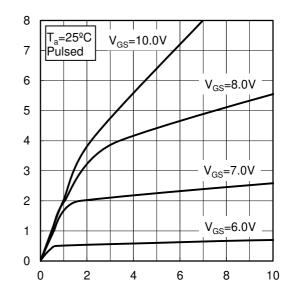
Junction Temperature : T<sub>i</sub> [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Typical Output Characteristics(II)

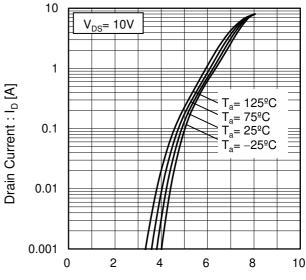


Drain - Source Voltage : V<sub>DS</sub> [V]

Drain Current : I<sub>D</sub> [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 280 Normarize Drain - Source Breakdown Voltage  $V_{GS} = 0V$ 270  $I_D = 1 \text{mA}$ 260 250 240 230 220 210 200 190 180 -50 0 50 100 150 Junction Temperature : T<sub>i</sub> [°C]

Fig.9 Typical Transfer Characteristics



Gate - Source Voltage :  $V_{GS}[V]$ 

Fig.10 Gate Threshold Voltage vs. Junction Temperature

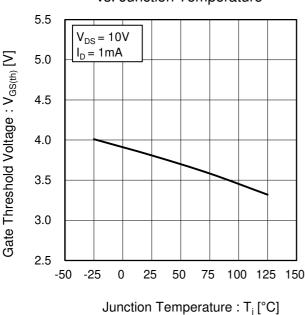
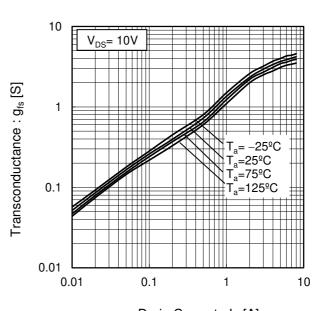


Fig.11 Transconductance vs. Drain Current



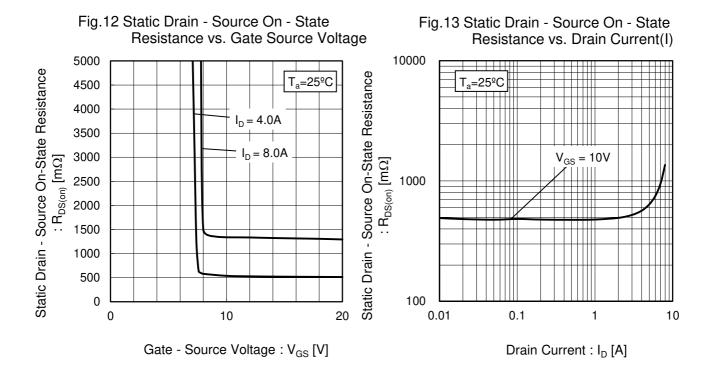
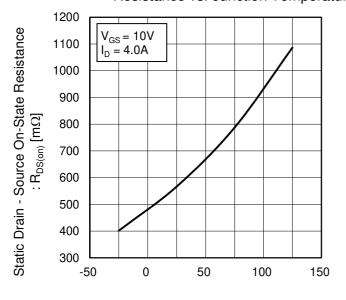


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T<sub>i</sub> [°C]

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

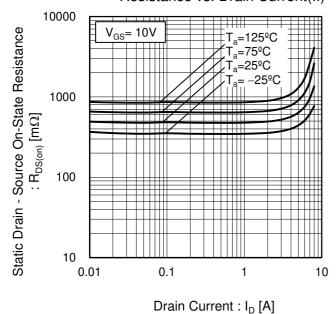


Fig.16 Drain Current Derating Curve

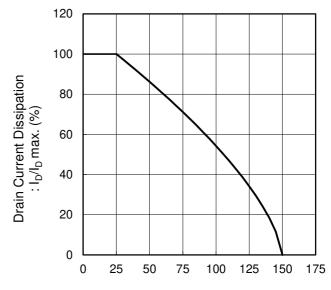
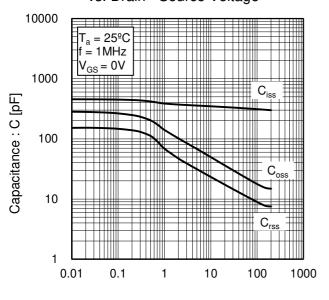
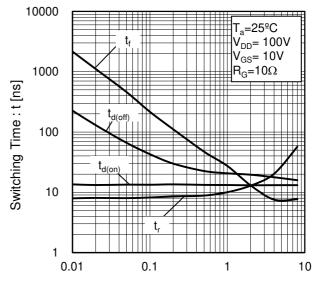


Fig.17 Typical Capacitance vs. Drain - Source Voltage



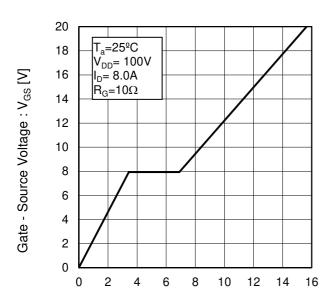
Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.18 Switching Characteristics

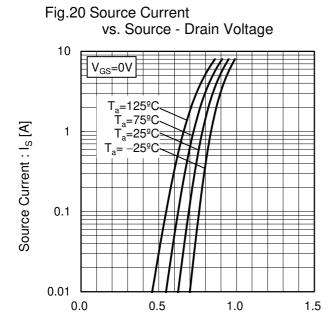


Drain Current: I<sub>D</sub> [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q<sub>g</sub> [nC]



Source-Drain Voltage :  $V_{SD}$  [V]

Source Current : I<sub>S</sub> [A]

## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

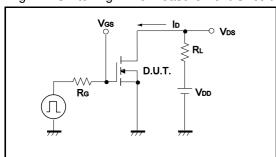


Fig.2-1 Gate Charge Measurement Circuit

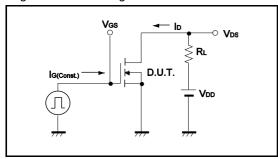


Fig.3-1 Avalanche Measurement Circuit

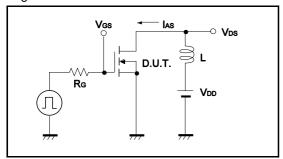


Fig.1-2 Switching Waveforms

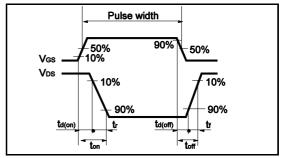


Fig.2-2 Gate Charge Waveform

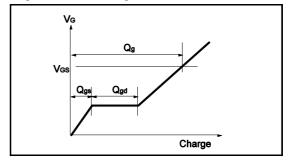
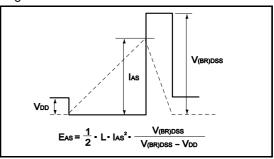
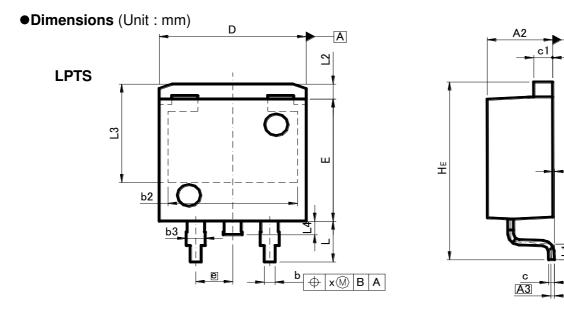
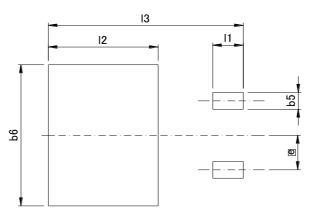


Fig.3-2 Avalanche Waveform



Α1





## Patterm of terminal position areas

DIM	MILIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
A1	0.00	0.30	0	0.012	
A2	4.30	4.70	0.169	0.185	
A3	0.:	25	0.0	01	
b	0.68	0.98	0.027	0.039	
b2	8.	90	0.3	35	
b3	1.14	1.44	0.045	0.057	
С	0.30	0.60	0.012	0.024	
c1	1.10	1.50	0.043	0.059	
D	9.80	10.40	0.386	0.409	
E	8.80	9.20	0.346	0.362	
е	2.	54	0.10		
HE	12.80	13.40	0.504	0.528	
L	2.70	3.30	0.106	0.13	
L1	0.90	1.50	0.035	0.059	
L2	1.10		0.043		
L3	7.25		0.285		
L4	1.0	00	0.0	39	
Lp	0.90	1.50	0.035	0.059	
х	_	0.25	_	0.01	

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b5	_	1.23	_	0.049
b6	-	10.40	-	0.409
11	-	2.10	-	0.083
12	-	7.55	_	0.297
13	_	13.40	_	0.528

Dimension in mm/inches

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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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